## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re l	Patent Application of	)		
Shun	oei YAMAZAKI et al.	)	ATTN:	New Applications
Based	d On: JP 2002-366158	)		
Filed:	December 18, 2002	)		
For:	METHOD FOR MANUFACTURING	)		
	SEMICONDUCTOR APPARATUS, A	AND)		
	SEMICONDUCTOR APPARATUS A	ND)		
	FLECTRIC APPLIANCE	)		

## INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56 and 37 C.F.R. 1.97-1.99, Applicant submits herewith a Form PTO-1449 listing references known to Applicant and requests that these references be made of record in the above identified application. Copies of the references listed are submitted herewith in accordance with 37 C.F.R. 1.98(a).

The Commissioner is hereby authorized to charge fees under 37 C.F.R. §§1.16, 1.17, 1.20(a), 1.20(b), 1.20(c), and 1.20(d) (except the Issue Fee) which may be required now or hereafter, or credit any overpayment to Deposit Account No. 50-2280. A duplicate copy of this sheet is attached.

Respectfully submitted,

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Attorney Docket Number

U.S. PATENT DOCUMENTS								
Examiner Initials*	Cite No.1	U.S. Patent Document		Name of Patent	Name of Patentee or Applicant of Cited	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	
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		N. Hayasaka, "Recent Status of Thin Wafer Chip (die) Mounting," SEMICON JAPAN 2002, Dec. 5, 2002, pages 3-8								
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